**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**
**WASHINGTON, D.C. 20231**

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| Inventor: **Denis Endisch, et al.** | Examiner: |
| Serial No: **Div. of 10/188433** | Art Unit: |
| Filed: **July 3, 2002** | |
| For: **Colloidal Silica Composite Films for Premetal Dielectric Applications** | |

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following preliminary amendment:

**IN THE CLAIMS**

Please cancel all pending claims and add the following claims addressing subject matter in application serial number 10/188433:

47. (Added) A method of forming a dielectric layer on a substrate comprising:

depositing a colloidal dispersion on a substrate;

curing the colloidal dispersion to form an intermediate layer; and

infiltrating the intermediate layer with a matrix material to form an infiltrated layer.

48. (Added) The method of claim 47, wherein the colloidal dispersion comprises particles of a dense material dispersed in a solvent.

49. (Added) The method of claim 48, wherein the dense material comprises a dielectric material or a material convertible to a dielectric material by oxidation or nitridation.